

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

1. – 51. (cancelled).

52. (currently amended) A non-volatile memory card system, comprising:

~~a card having:~~

a bottom surface;

a top surface opposite the bottom surface, the top surface having a raised portion;

a bottom edge extending between the top and bottom surfaces;

a top edge opposite the bottom edge;

a pair of side edges extending between the top and bottom surfaces and the top and bottom edges, one of the pair of side edges including a notch;

~~, a front surface, a rear surface and two side surfaces, said card includes~~

~~a set of contacts on said bottom surface adjacent the top edge, said top surface having a raised portion, one of said side surfaces includes a notch portion and an angle portion;~~

a circuit board in said card;

a plurality of non-volatile storage elements enclosed within said card and connected to said circuit board;

molding compound encapsulating the printed circuit board and plurality of non-volatile storage elements, the molding compound generally defining the top and bottom surfaces, the top and bottom edges and the pair of side edges;

test pins, exposed through a surface of the molding compound, for testing operation of the non-volatile storage elements;

a conformal coating removably covering the test pins; and

passive electrical elements enclosed within said card and connected to said circuit board, said passive electrical elements are positioned in a part of said card at least partially defined by said raised portion.

53. (currently amended) A non-volatile memory card ~~system~~ according to claim 52, wherein:

said non-volatile storage elements are flash memory cells.

54. (cancelled)

55. (currently amended) A non-volatile memory card ~~system~~ according to claim 52, further comprising:

a controller element enclosed within said card and connected to said circuit board.

56. (currently amended) A non-volatile memory card ~~system~~ according to claim 55, wherein:

said passive electrical elements are in communication with said controller.

57. (cancelled)

58. (currently amended) A non-volatile memory card ~~system~~ according to claim 52, wherein:

said passive electrical elements are capacitors.

59. (cancelled)

60. (currently amended) A non-volatile memory card ~~system~~ according to claim 52, wherein:

said raised portion provides a grip to grab said card.

61. (cancelled)

62. (currently amended) A non-volatile memory card system according to claim 52, wherein:

said non-volatile storage elements are flash memory devices in a flash memory array; and
said passive electrical elements are capacitors.

63. (currently amended) A non-volatile memory card system, comprising:

a bottom surface including a first planar portion and a second planar portion
residing in a different plane than the first planar portion;

a top surface opposite the bottom surface, the top surface having a raised portion;

a bottom edge extending between the top and bottom surfaces;

a top edge opposite the bottom edge;

a pair of side edges extending between the top and bottom surfaces and the top
and bottom edges, one side edge of the pair of said edges including first and second
sections extending generally parallel to each other and a third section extending between
the first and second sections and forming an oblique angle with each of the first and
second sections, one of the first and second sections including a notch;

a set of contacts on said bottom surface, in the first planar portion and adjacent the
top edge;

a circuit board in said card;

~~a card having a first dimension and a second dimension, said card has a first
thickness along a first portion of said first dimension and a second thickness along a
second portion of said first dimension, said second thickness is greater than said first
thickness, said card having a side surface, said side surface includes a notch portion and
an angled portion;~~

a plurality of non-volatile storage elements enclosed within said card; and

passive electrical elements enclosed within said card, said passive electrical
elements are positioned in said second portion.

64. (currently amended) A non-volatile memory card ~~system~~ according to claim 63, wherein:

said passive electrical elements are capacitors.

65. (currently amended) A non-volatile memory card ~~system~~ according to claim 64, wherein the first and second planar portions are provided so that a thickness of the card at a point in the first planar section is smaller than a thickness of the card at a point in the second planar section ÷

~~said first dimension is length;~~

~~said second dimension is width; and~~

said non-volatile storage elements are flash memory devices.

66. (currently amended) A non-volatile memory card ~~system~~ according to claim 63, wherein the first planar portion is an area substantially occupied by the set of contacts on the bottom surface ÷

~~said first dimension is length; and~~

~~said second dimension is width.~~

67. (currently amended) A non-volatile memory card ~~system~~ according to claim 63, wherein:

said passive electrical elements are in electrical communication with said non-volatile storage elements.

68. (cancelled)

69. (currently amended) A non-volatile memory card ~~system~~ according to claim 63 ~~68~~, further comprising:

a controller, said controller is positioned within said card and is in communication with said non-volatile storage elements; and

~~a set of electrical contacts on an external surface of said card, said~~ the set of electrical contacts are in communication with said controller.

70. (currently amended) A non-volatile memory card ~~system~~ according to claim 63, wherein:

said non-volatile storage elements are flash memory devices.

71-72. (cancelled)

73. (currently amended) A non-volatile memory card ~~system~~ according to claim 63 ~~72~~, wherein:

said card includes molding material encapsulating said plurality of non-volatile storage elements and said passive electrical elements, said molding material defines said top surface and said side surface.

74. – 79. (cancelled)

80. (currently amended) A non-volatile memory card ~~system~~, comprising:

a bottom surface;

a top surface opposite the bottom surface, the top surface having a raised portion;

a bottom edge extending between the top and bottom surfaces;

a top edge opposite the bottom edge;

a pair of side edges extending between the top and bottom surfaces and the top and bottom edges, one side edge of the pair of said edges including first and second sections extending generally parallel to each other and a third section extending between the first and second sections and forming an oblique angle with each of the first and second sections, one of the first and second sections including a notch;

a set of contacts on said bottom surface, in the first planar portion and adjacent the top edge;

a circuit board in said card;

~~a removable peripheral card having a first dimension and a second dimension, said removable peripheral card has a first thickness along a first portion of said first dimension and a second thickness along a second portion of said first dimension, said second thickness is greater than said first thickness, said removable peripheral card having a side surface, said side surface includes a notch portion;~~

non-volatile storage elements enclosed within said peripheral card; and

a passive electrical component enclosed within said removable peripheral card, said passive electrical element is positioned in said second portion.

81. (cancelled)

82. (currently amended) A non-volatile memory card system according to claim 80, further comprising:

molding compound encapsulating the printed circuit board and plurality of non-volatile storage elements, the molding compound generally defining the top and bottom surfaces, the top and bottom edges and the pair of side edges;

test pins, exposed through a surface of the molding compound, for testing operation of the non-volatile storage elements; and

a conformal coating removably covering the test pins

~~a circuit board;~~

~~a passive electrical component connected to said circuit board;~~

~~a flash memory chip connected to said circuit board;~~

~~molding material forming a peripheral card having a top surface, a front surface, a rear surface and two side surfaces, one of said side surfaces has an angle portion and a notch portion, said top surface having a raised portion adjacent said rear surface, said peripheral card having a first section and a second section, said second section is thicker than said first section to accommodate said passive electrical component, said circuit board and said flash memory chip are positioned in said molding material.~~

83. (currently amended) A non-volatile memory card system, comprising:

- a bottom surface including a first planar portion and a second planar portion residing in a different plane than the first planar portion, the card being thinner at the first planar portion than at the second planar portion;
- a top surface opposite the bottom surface, the top surface having a raised portion;
- a bottom edge extending between the top and bottom surfaces;
- a top edge opposite the bottom edge;
- a pair of side edges extending between the top and bottom surfaces and the top and bottom edges, one side edge of the pair of said edges including first and second sections extending generally parallel to each other and a third section extending between the first and second sections and forming an oblique angle with each of the first and second sections, one of the first and second sections including a notch;
- ~~a card having a bottom surface, a top surface, a front surface, a rear surface and two side surfaces, said card includes a set of contacts on said bottom surface, said top surface having a raised portion, one of said side surfaces includes an angle portion;~~
- a circuit board in said card;
- a plurality of non-volatile storage elements enclosed within said card and connected to said circuit board;
- molding compound encapsulating the printed circuit board and plurality of non-volatile storage elements;
- test pins, exposed through a surface of the molding compound, for testing operation of the non-volatile storage elements;
- a conformal coating removably covering the test pins; and
- a passive electrical element enclosed within said card and connected to said circuit board, said passive electrical elements is positioned in a part of said card at least partially defined by said raised portion.

84. (currently amended) A non-volatile memory card system according to claim 83, wherein:

~~said card comprises molding material forming said top surface and said one of said side surfaces, said molding material defines said raised portion and said angle portion~~ the molding compound generally defines the top and bottom surfaces, the top and bottom edges and the pair of side edges.

85. (currently amended) A non-volatile memory card ~~system~~ according to claim 83, wherein:

~~said card comprises molding material forming said top surface and said side surfaces, said molding material does not form said bottom surface,~~ the molding compound generally defines the top surface, the top and bottom edges and the pair of side edges and said circuit board defines said bottom surface.

86. (cancelled)